

Product Summary

V_{RRM} (V)	I_O (A)	V_F Max (V) @ +25°C	I_R Max (μA) @ +25°C
100	2	0.83	0.15

Features and Benefits

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Interlocking Clip Design for High Surge Current Capacity
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **The SDM2100S1FQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.**

<https://www.diodes.com/quality/product-definitions/>

Description and Applications

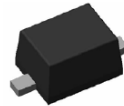
The SDM2100S1FQ is a single rectifier packaged in SOD123F. Offering low V_F , low power loss and high efficiency, this device is ideal for use in general rectification applications as a:

- Boost Diode
- Blocking Diode

Mechanical Data

- Case: SOD123F
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (E3)
- Polarity: Cathode Band
- Weight: 0.015 grams (Approximate)

SOD123F



Top View

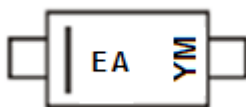
Ordering Information (Note 4)

Part Number	Case	Packaging
SDM2100S1FQ-7	SOD123F	3,000/Tape & Reel

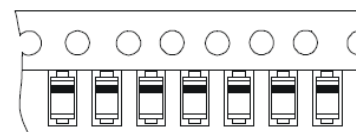
- Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information

Cathode Pin



EA = Product Type Marking Code
YM = Date Code Marking
Y = Year (ex.: H = 2020)
M = Month (ex.: 9 = September)
Bar Denotes Cathode Pin



Bar Denotes Cathode Pin

Date Code Key

Year	2016	...	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	D	...	H	I	J	K	L	M	N	O	P	R
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derating current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	100	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _{RM}		
Average Rectified Output Current	I _O	2	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	50	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Case (Note 5)	R _{θJC}	40	°C/W
Typical Thermal Resistance Junction to Ambient (Note 5)	R _{θJA}	100	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +175	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V _R	100	—	—	V	I _R = 1.0mA
Forward Voltage Drop	V _F	—	0.78 0.64	0.83 0.74	V	I _F = 2A, T _J = +25°C I _F = 2A, T _J = +125°C
Leakage Current (Note 6)	I _R	—	0.035 70	0.15 500	μA	V _R = 100V, T _J = +25°C V _R = 100V, T _J = +125°C
Total Capacitance	C _T	—	42	—	pF	V _R = 4V, f = 1MHz

Notes: 5. Device mounted on FR-4 substrate, 0.4"*0.5", 2oz, single-sided, PC boards with 0.2"*0.25" copper pad.
6. Short duration pulse test used to minimize self-heating effect.

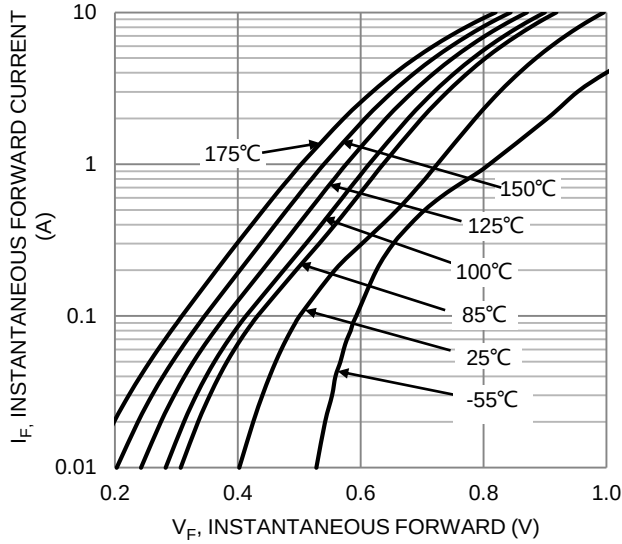


Figure 1. Typical Forward Characteristics

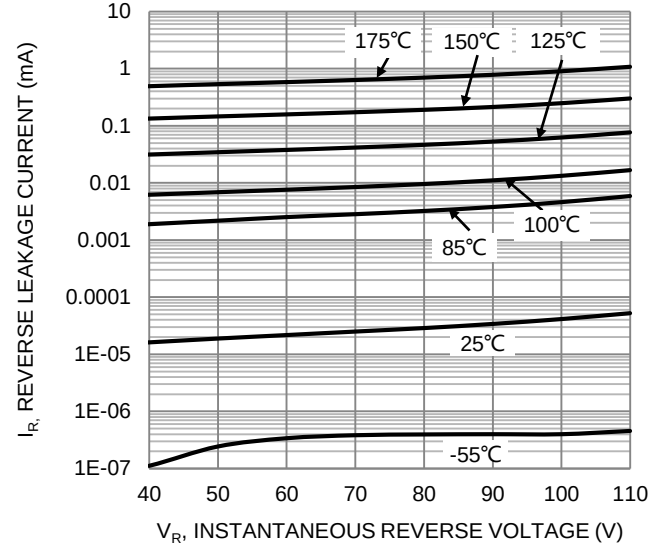


Figure 2. Typical Reverse Characteristics

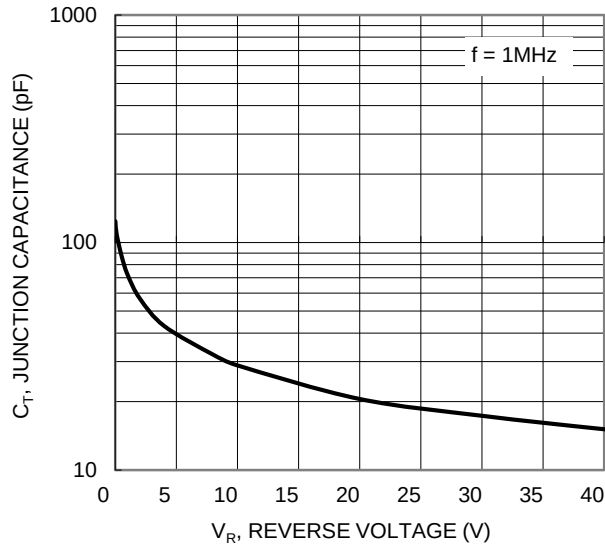


Figure 3. Typical Junction Capacitance

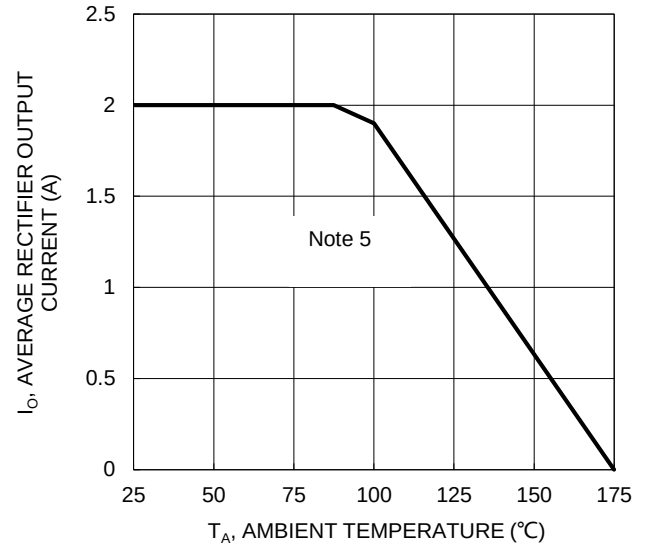


Figure 4. DC Forward Current Derating

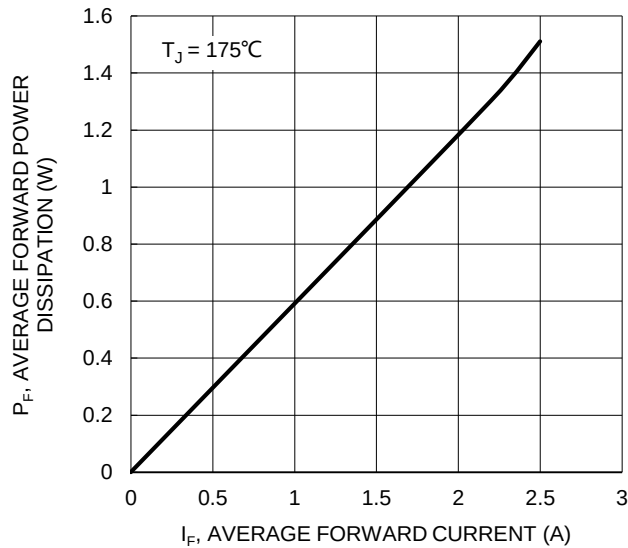
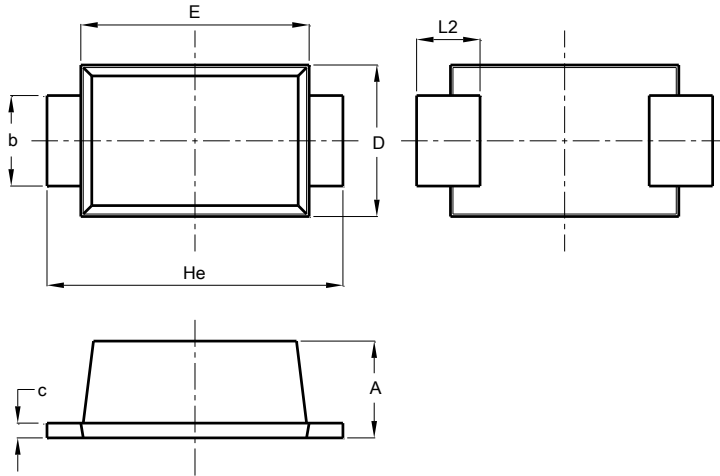


Figure 5. Forward Power Dissipation

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOD123F

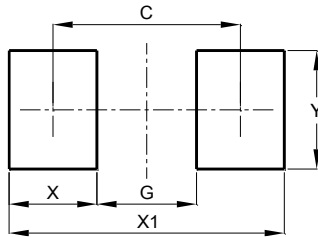


SOD123F			
Dim	Min	Max	Typ
A	0.81	1.15	-
b	0.80	1.05	-
c	0.05	0.30	-
D	1.70	1.90	1.80
E	2.60	2.80	2.70
He	3.30	3.70	3.50
L2	0.35	0.85	-
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOD123F



Dimensions	Value (in mm)
C	2.86
G	1.52
X	1.34
X1	4.20
Y	1.80

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